

**IN THE CLAIMS**

1. (Currently Amended) A UV energy curable tape comprising:  
a support layer;  
an adhesive material positioned on said support layer, and including a UV energy curable oligomer, a UV energy initiator, and a material which ~~emits~~ starts to emit optical light of a first type when said tape is becomes substantially fully cured ~~positioned on said support layer~~.
2. (Original) The UV energy curable tape of claim 1, wherein said adhesive material comprises an acrylate oligomer.
3. (Original) The UV energy curable tape of claim 1, wherein said UV energy curable oligomer comprises a material capable of reacting with radicals to form longer chain polymers.
4. (Original) The UV energy curable tape of claim 1, wherein said UV energy initiator comprises a photoinitiator.
5. (Original) The UV energy curable tape of claim 4, wherein said photoinitiator includes diphenyl groups that create radicals when exposed to UV energy.
6. (Original) The UV energy curable tape of claim 1, wherein said material which emits optical light comprises UV sensitive ink.
7. (Original) The UV energy curable tape of claim 6, wherein said material which emits optical light comprises from about .001 weight percent to about 20 weight percent of said tape.

8. (Original) The UV energy curable tape of claim 1, wherein said material which emits optical light comprises UV sensitive dye
9. (Original) The UV energy curable tape of claim 1, wherein substantially fully cured comprises the absorption of about 5 millijoules/cm<sup>2</sup> to about 10 joules/cm<sup>2</sup> of UV energy into said tape.
10. (Cancelled).
11. (Currently Amended) A UV energy curable tape comprising:  
a support layer including a material which ~~emits~~ starts to emit optical light of a first type when said tape is becomes substantially fully cured; and  
an adhesive material positioned on said support layer having a UV energy curable oligomer and a UV energy initiator as part thereof.
12. (Original) The UV energy curable tape of claim 11, wherein said adhesive material comprises an acrylate oligomer.
13. (Original) The UV energy curable tape of claim 11, wherein said UV energy curable oligomer comprises a material capable of reacting with radicals to form longer chain polymers.
14. (Original) The UV energy curable tape of claim 11, wherein said UV energy initiator comprises a photoinitiator.

15. (Original) The UV energy curable tape of claim 14, wherein said photoinitiator includes diphenyl groups that create radicals when exposed to UV energy.
16. (Original) The UV energy curable tape of claim 11, wherein said material which emits optical light comprises UV sensitive ink.
17. (Original) The UV energy curable tape of claim 16, wherein said material which emits optical light comprises from about .001 weight percent to about 20 weight percent of said tape.
18. (Original) The UV energy curable tape of claim 11, wherein said material which emits optical light comprises UV sensitive dye.
19. (Original) The UV energy curable tape of claim 11, wherein substantially fully cured comprises the absorption of about 5 millijoules/cm<sup>2</sup> to about 10 joules/cm<sup>2</sup> of UV energy into said tape.
20. (Cancelled).
21. (Original) A method of making a semiconductor chip comprising the steps of:  
providing a semiconductor wafer substrate having a first surface;  
forming a layer of UV energy curable tape on said first surface, said tape including a material which emits optical light when substantially fully cured; and  
applying UV energy to said layer of UV energy curable tape until said material emits optical light.

22. (Original) The method of claim 21, further including the step of dicing said semiconductor wafer into at least two semiconductor chips after said step of forming said layer of UV energy curable tape on said first surface.

23. (Original) The method of claim 22, wherein said applying UV energy comprises shining UV light on said layer of UV energy curable tape in the amount of from about 5 millijoules/cm<sup>2</sup> to about 10 joules/cm<sup>2</sup>.

24. (Original) The method of claim 23, further including the step of removing said semiconductor chips from said UV curable tape after said tape is substantially fully cured.

25. (Original) A semiconductor chip formed by said method of claim 21.

26. (Original) A method of making a semiconductor chip comprising the steps of:

providing a layer of UV energy curable tape on a support layer, said support layer including a material which emits optical light when said tape is substantially cured;

placing said UV energy curable tape on a surface of a semiconductor wafer; and

applying UV light on and through said support layer until said support layer emits optical light.

27. (Original) The method of claim 26, further including the step of dicing said semiconductor wafer into at least two semiconductor chips after said step of placing said UV energy curable tape on said surface of said semiconductor wafer.

28. (Original) The method of claim 27, wherein said applying step includes shining said UV light on and through said support layer in the amount of from about 5 millijoules/cm<sup>2</sup> to about 10 joules/cm<sup>2</sup>.

29. (Original) A semiconductor chip formed by said method of claim 26.

30. (New) The UV energy curable tape of Claim 1, wherein the light emitting material emits light of a second type, different from said first type, as the tape is being cured, and the type of light emitted by said light emitting material changes from said second type to said first type when the type becomes substantially fully cured.

31. (New) The UV energy curable tape of Claim 1, for use with a given substrate, and wherein the amount of energy needed to cause the light emitting material to emit the first type of light matches the amount of energy required to substantially fully cure the tape, thereby to facilitate completely removing the tape from the given substrate.